+357 96 030922
info@marketpublishers.com

Global High Thermally-conductive Epoxy Molding Compound Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

https://marketpublishers.com/r/G1141BF16D9BEN.html
Date: November 2025
Pages: 95
Price: US$ 3,480.00 (Single User License)
ID: G1141BF16D9BEN

Abstracts

According to our (Global Info Research) latest study, the global High Thermally-conductive Epoxy Molding Compound market size was valued at US$ 640 million in 2024 and is forecast to a readjusted size of USD 1298 million by 2031 with a CAGR of 11.1% during review period.

In this report, we will assess the current U.S. tariff framework alongside international policy adaptations, analyzing their effects on competitive market structures, regional economic dynamics, and supply chain resilience.

A High Thermally-Conductive Epoxy Molding Compound (HTC EMC) is a composite material consisting of epoxy resin, thermally conductive fillers, curing agents, and additives. It is specifically engineered to encapsulate and protect electronic components while facilitating efficient heat dissipation. HTC EMCs are widely used in power electronics, automotive modules, LEDs, and semiconductor packaging to manage thermal loads and enhance reliability.

This report is a detailed and comprehensive analysis for global High Thermally-conductive Epoxy Molding Compound market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

+357 96 030922
info@marketpublishers.com

Key Features:

Global High Thermally-conductive Epoxy Molding Compound market size and forecasts, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/Ton), 2020-2031

Global High Thermally-conductive Epoxy Molding Compound market size and forecasts by region and country, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/Ton), 2020-2031

Global High Thermally-conductive Epoxy Molding Compound market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (Tons), and average selling prices (US$/Ton), 2020-2031

Global High Thermally-conductive Epoxy Molding Compound market shares of main players, shipments in revenue ($ Million), sales quantity (Tons), and ASP (US$/Ton), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for High Thermally-conductive Epoxy Molding Compound

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global High Thermally-conductive Epoxy Molding Compound market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Sumitomo Bakelite, KYOCERA GROUP GLOBAL SITE, SolEpoxy, Inc., CAPLINQ, Henkel, Resonac, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

+357 96 030922
info@marketpublishers.com

Market Segmentation

High Thermally-conductive Epoxy Molding Compound market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

- Powder
- Particles

Market segment by Application

- Power Module
- Mold Under Fill (MUF)

Major players covered

- Sumitomo Bakelite
- KYOCERA GROUP GLOBAL SITE
- SolEpoxy, Inc.
- CAPLINQ
- Henkel
- Resonac

Market segment by region, regional analysis covers

+357 96 030922
info@marketpublishers.com

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe High Thermally-conductive Epoxy Molding Compound product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of High Thermally-conductive Epoxy Molding Compound, with price, sales quantity, revenue, and global market share of High Thermally-conductive Epoxy Molding Compound from 2020 to 2025.

Chapter 3, the High Thermally-conductive Epoxy Molding Compound competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the High Thermally-conductive Epoxy Molding Compound breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2020 to 2031.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2020 to 2031.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2020 to 2025.and High Thermally-conductive Epoxy Molding Compound market forecast, by regions, by Type, and by Application, with sales and revenue, from 2026 to 2031.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces

+357 96 030922
info@marketpublishers.com

analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of High Thermally-conductive Epoxy Molding Compound.

Chapter 14 and 15, to describe High Thermally-conductive Epoxy Molding Compound sales channel, distributors, customers, research findings and conclusion.

+357 96 030922
info@marketpublishers.com

Contents

+357 96 030922
info@marketpublishers.com

3 COMPETITIVE ENVIRONMENT: HIGH THERMALLY-CONDUCTIVE EPOXY

+357 96 030922
info@marketpublishers.com

MOLDING COMPOUND BY MANUFACTURER

4 CONSUMPTION ANALYSIS BY REGION

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

I would like to order

Product name: Global High Thermally-conductive Epoxy Molding Compound Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

Product link: https://marketpublishers.com/r/G1141BF16D9BEN.html

Price: US$ 3,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/G1141BF16D9BEN.html